

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION

WILLEMS VAN DIJK, et al

Appln. No.: Not Assigned

Group Art Unit: Not Assigned

Filed: Herewith

Examiner: Not Assigned

For: OBJECT POSITIONING METHOD FOR A
LITHOGRAPHIC PROJECTION APPARATUS

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February 8, 2001

PRELIMINARY AMENDMENT

Hon. Commissioner of Patents
Washington, D.C. 20231

Sir:

Prior to the initial examination, please amend the above-identified patent application as follows:

IN THE ABSTRACT:

Please replace the Abstract of the Disclosure with the Abstract of the Disclosure attached on a separate sheet.

IN THE SPECIFICATION:

Please amend the specification as follows:

Page 1, line 1, insert and center:

--BACKGROUND OF THE INVENTION--;

between lines 1 and 2, insert: --1. Field of the Invention--;

line 2, delete "particular" and insert --particularly--;

between lines 10 and 14 insert: --2. Background of the Related Art--; and

line 14, before "should" insert --or "mask".

Page 2, line 27, delete "in one go" and insert --at once--.

Page 3, line 21, before "reflective" and insert --and/or--; and

line 22, after ", and" and insert --including--.

Page 6, between lines 11 and 15 insert:

--SUMMARY OF THE INVENTION--.

Page 9, line 1, insert:

--BRIEF DESCRIPTION OF THE DRAWINGS--; and

line 15, insert:

--DETAILED DESCRIPTION OF THE INVENTION--.

Page 13, line 25, delete "Whilst" and insert --While--.

IN THE CLAIMS:

Please amend the claims as follows:

1. (Amended) A method of positioning an object at a required position on an object table in a lithographic projection apparatus, comprising:

[a radiation system for supplying a projection beam of radiation;

a first object table for holding patterning means;

a second object table for holding a substrate; and

a projection system for projecting the patterned beam onto a target portion of the substrate, characterised in that said method comprises the following steps:]

[a first placement step in which the] placing an object [is placed] at a first position on [the] a first object table;

[a] measuring [step in which] a displacement between the first position of the object and [the] a required position of the object [is determined];

[a] removing [step in which] the object [is released and removed] from the first object table;

[a] moving [step in which] the object and the first object table [are moved] relatively to each other by substantially the said displacement, in a direction substantially parallel to the plane of the table; and

[a second placement step in which] placing the object [is placed] at substantially the required position on the first object table.

2. (Amended) A method according to claim 1, wherein said measuring [step] comprises aligning a first mark on the object to a second, reference mark.

3. (Amended) A method according to claim 2, wherein said second mark is located on the [first or the second] one of the first object table and a second object table.

4. (Amended) A method according to claim 1 [or 2], wherein [the patterning means comprises] a mask is held by the first object table.

5. (Amended) A method according to claim [4] 2, wherein said second mark is located on [the] one of a mask [or the] and a substrate.

6. (Amended) A method according to claim 1, wherein said measuring [step] is accomplished using imaging means to determine the displacement between the first position of the object and the required position of the object.

7. (Amended) A method according to [any of the proceeding claims] claim 1, wherein said measuring [step] comprises processing information about the first position of the object, together with information regarding the required position of the object[, in calculation means,] to determine said displacement.

11. (Amended) A method of positioning a substrate at a required position on a substrate table, [characterised in that] said method [comprises the following steps] comprising:

[a first placement step in which] placing the substrate [is placed] at a first position on the table;

[a] measuring [step in which] a displacement between the first position of the substrate and [the] a required position of the substrate [is determined];

[a] removing [step in which] the substrate [is released and removed] from the table;

[a] moving [step in which] the substrate and the table [are moved] relatively to each other by substantially the said displacement, in a direction substantially parallel to the plane of the table; and

[a second placement step in which] placing the substrate [is placed] at substantially the required position on the table.

12. (Amended) A device manufacturing method comprising [the steps of]:

(a) providing a [second object] substrate table with a substrate which is at least partially covered by a layer of radiation-sensitive material;

(b) [using patterning means to endow the] patterning a projection beam [with] to produce a pattern in its cross-section; and

(c) projecting the patterned beam onto a target portion of the layer of radiation-sensitive material [, characterised in that, prior to step (c), the following actions are performed]:

[a first placement step in which] prior to said projecting, placing the substrate [is placed] at a first position on the [second object] substrate table;

[a] measuring [step in which] a displacement between the first position of the substrate and [the] a required position of the substrate [is determined];

[a] removing [step in which] the substrate [is released and removed] from the [second object] substrate table;

[a] moving [step in which] the substrate and the [second object] substrate table [are moved] relatively to each other by substantially the said displacement, in a direction substantially parallel to the plane of the second object table; and

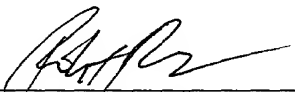
[a second placement step in which] placing the substrate [is placed] at substantially the required position on the second object table.

REMARKS

Claims 1-13 are pending in this application. By this Preliminary Amendment, the specification and the Abstract of the Disclosure have been amended, and claims 1-7 and 11-12 have been amended to remove multiple dependencies and to conform to U.S. practice. Prompt and favorable consideration on the merits is respectfully requested.

Respectfully submitted,

PILLSBURY WINTHROP LLP

By 
Robert C.F. Perez
Reg. No. 39328
Tel. No. (202)861-3777
Fax No. (202)822-0944

JSB/RCP/mjb

1100 New York Avenue, N.W., 9th Floor
Washington, DC 20005-3918
(202)861-3000